FIG. 1

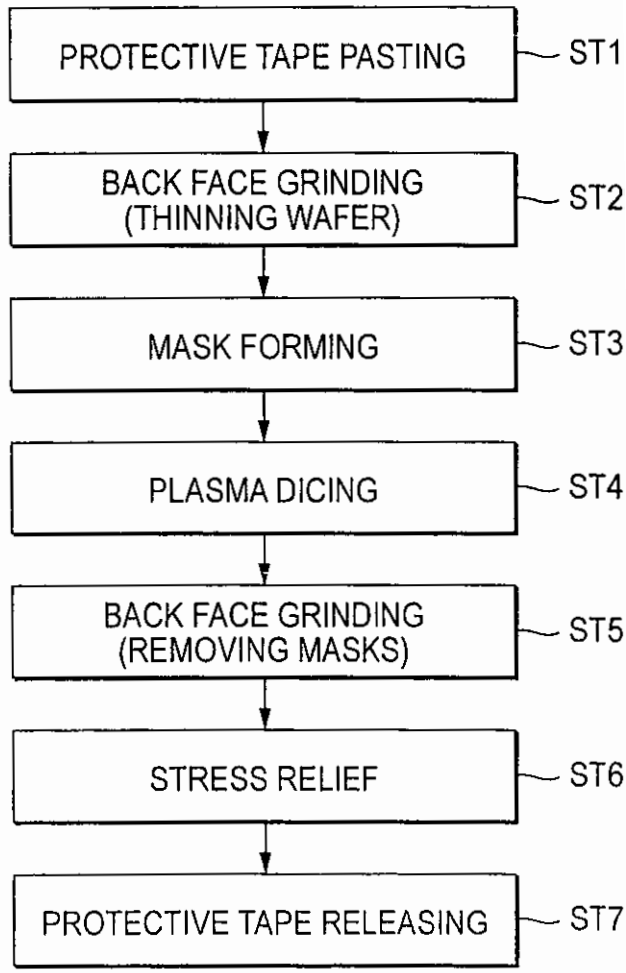

PROTECTIVE TAPE PASTING
ST1
BACK FACE GRINDING (THINNING WAFER)
ST2
MASK FORMING
ST3
PLASMA DICING
ST4
BACK FACE GRINDING (REMOVING MASKS)
ST5
STRESS RELIEF
ST6
PROTECTIVE TAPE RELEASING
ST7

FIG. 2A

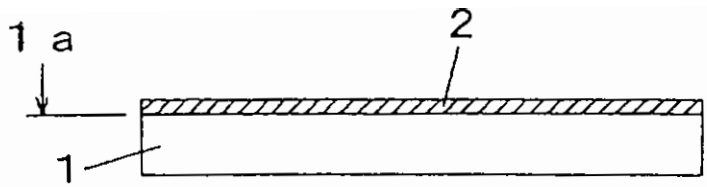


FIG. 2B

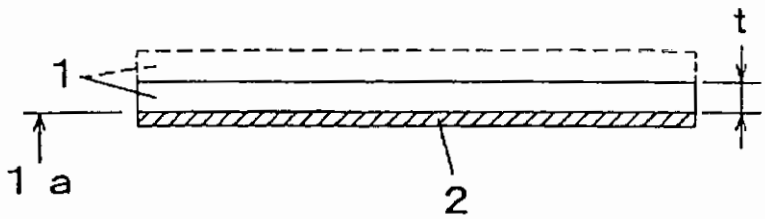


FIG. 2C

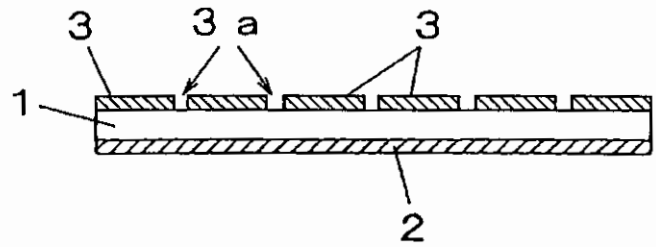


FIG. 2D

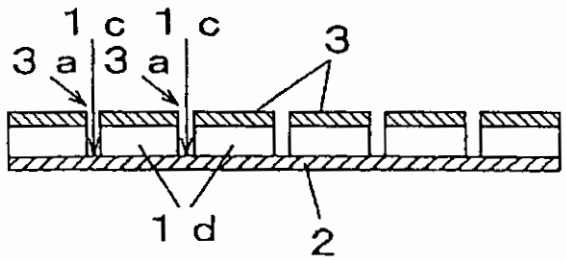


FIG. 2E

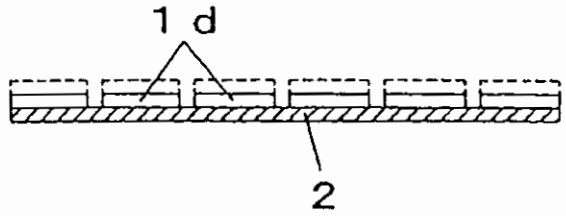


FIG. 2F

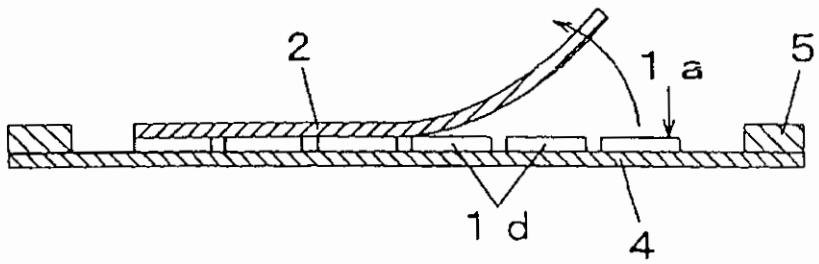


FIG. 3

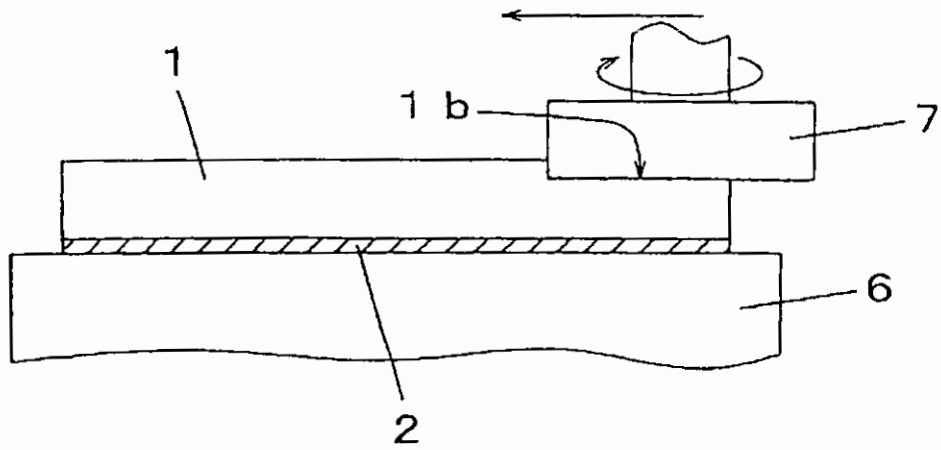


FIG. 4

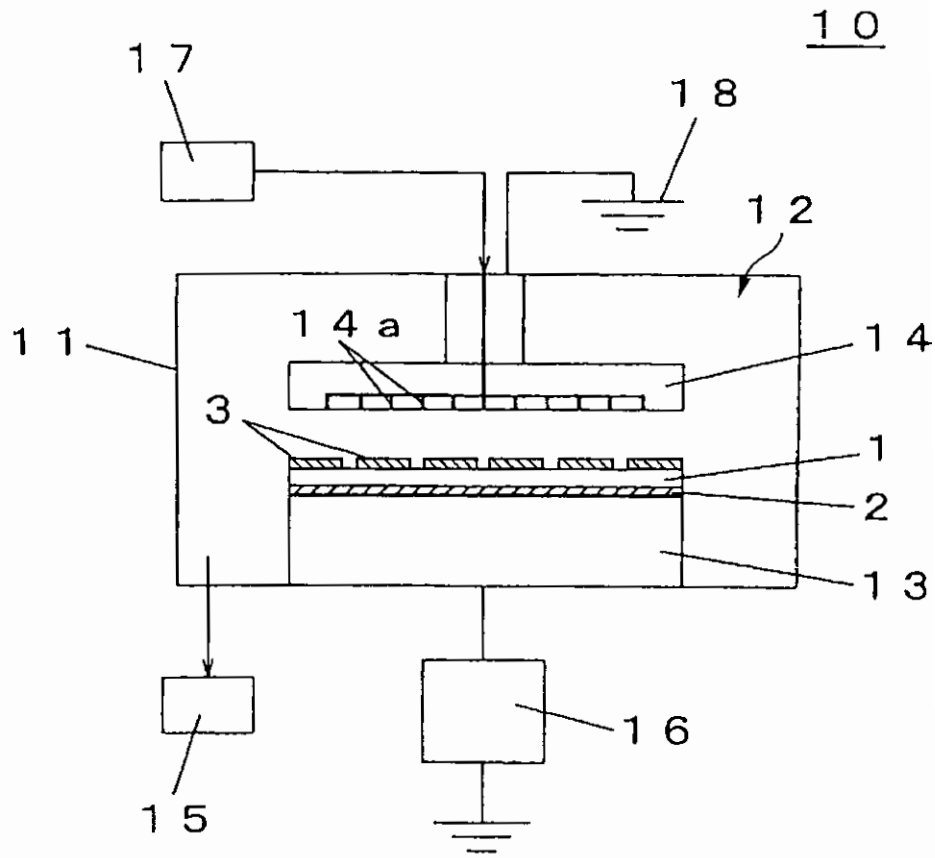


FIG. 5

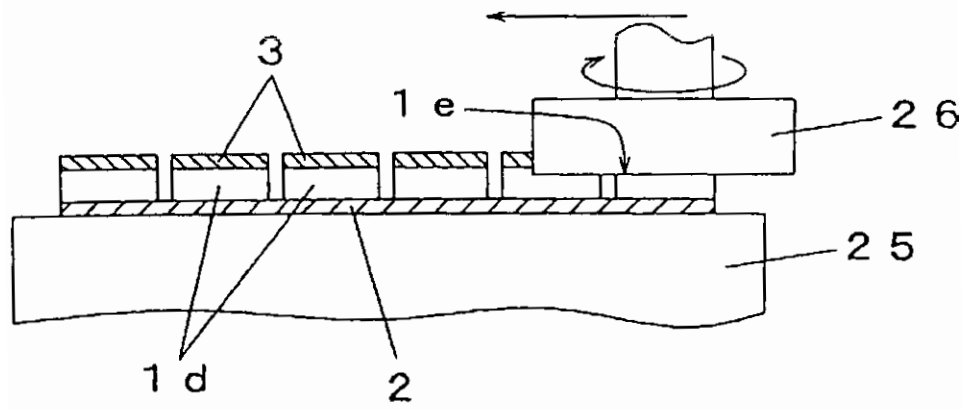


FIG. 6

